Open Access at IEEE

Workflow for Authors - 2023

Background

IEEE provides discounted fully OA APC Tokens for CONCERT member schools that subscribe to the IEL database:：

- 1) When an affiliated corresponding author publishes a paper in an IEEE Fully OA journal, an institutional discount offer will automatically apply.
- 2) During the submission process, the corresponding author shall enter the school email address and/or the institution data , as it will be used to match the author with an institutional OA account.
- 3) Authors can use a discounted APC Token USD1,560** to publish a manuscript.
- 4) This offer cannot be combined with any other promotion.
- 5) Token Request will be submitted to the institution administrator for review and approval .
- 6) If a different APC offer is preferred, you can contact the administrator at your institution or ieee_oa@hintoninfo.com to decline the special offer. After the administrator denies the default request, the corresponding author will receive an email from RSLC to pay the APC

* https://open.ieee.org/about/

IEEE Fully OA Journals include IEEE Topical Journals and IEEE *Access*

**2023 Standard APC for IEEE Fully OA Journals = USD1,950

Open Access allows authors to publish in respected, high-quality, scholarly journals, while also complying with the latest open access policies. IEEE makes the transition simple by providing several options for authors to choose from:

- Fully Open Access Topical Journals →
- Hybrid Journals →
- IEEE *Access* (Multidisciplinary Open Access Journal) →

Author Process

Step 1 **Submission process**

SCHOLARONE™

Step 2 **Post acceptance**

IEEE

IEEE Electronic Copyright Form

Step 3 **RightsLink for Scientific Communications (RLSC)**

Copyright Clearance Center | RightsLink

Step 4 **Pay OA APC in TWD**

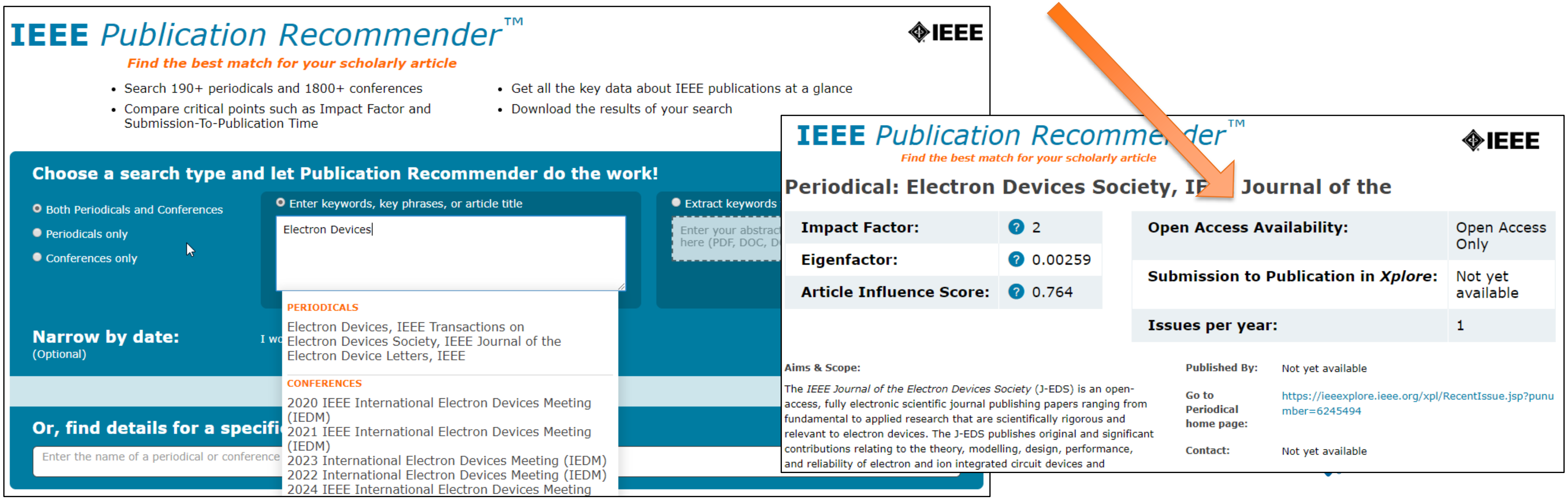
藍新金流
NewebPay

Submission – Step 1

https://publication-recommender.ieee.org/home

IEEE Publication Recommender helps authors find the most suitable journal and displays journal’s OA Status with submission URL

Note: Open Access status clearly displayed in results.



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Choose a search type and let Publication Recommender do the work!

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○ Periodicals only
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○ Enter keywords, key phrases, or article title

Electron Devices

PERIODICALS
Electron Devices, IEEE Transactions on
Electron Devices Society, IEEE Journal of the
Electron Device Letters, IEEE

CONFERENCES
2020 IEEE International Electron Devices Meeting (IEDM)
2021 IEEE International Electron Devices Meeting (IEDM)
2023 International Electron Devices Meeting (IEDM)
2022 International Electron Devices Meeting (IEDM)
2024 IEEE International Electron Devices Meeting

○ Extract keywords

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Or, find details for a specifi

Enter the name of a periodical or conference

IEEE *Publication Recommender*™

Find the best match for your scholarly article

Periodical: Electron Devices Society, IE Journal of the

Impact Factor:	2
Eigenfactor:	0.00259
Article Influence Score:	0.764

Open Access Availability:	Open Access Only
Submission to Publication in *Xplore*:	Not yet available
Issues per year:	1

Aims & Scope:

The *IEEE Journal of the Electron Devices Society* (J-EDS) is an open-access, fully electronic scientific journal publishing papers ranging from fundamental to applied research that are scientifically rigorous and relevant to electron devices. The J-EDS publishes original and significant contributions relating to the theory, modelling, design, performance, and reliability of electron and ion integrated circuit devices and

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Submission – Step 1 – in IEEE *Xplore*

https://ieeexplore.ieee.org/browse/periodicals/title?refinements=Publisher:IEEE&showActiveTitlesOnly=true

Browse Journals & Magazines

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Search by keywords

Browse Titles

A | B | C | D | E | F | G | H | I | J | K | L | M | N | O | P | Q | R | S | T | U | V | W | X | Y | Z | 0 - 9 | All

Showing **1-25** of **228**

Filters Applied: IEEE ×

Show

● All Results

○ Open Access Titles Only

○ Titles with Some Open Access

☑ Show active titles only

Fully OA Journals

IEEE Access

Publisher: IEEE **Years:** 2013 - Present Most Recent Issue

IEEE Aerospace and Electronic Systems Magazine

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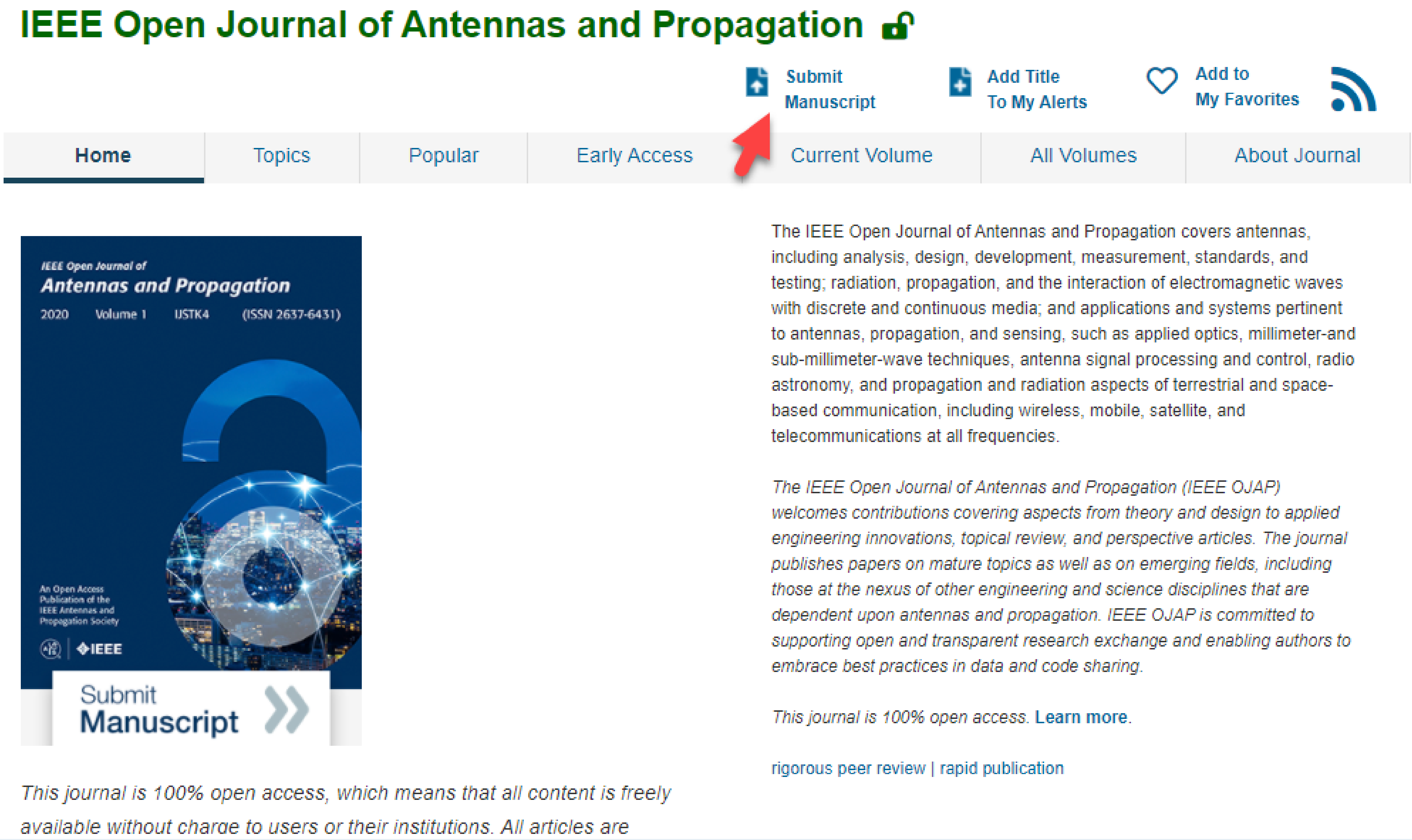
IEEE Transactions on Aerospace and Electronic Systems

Publisher: IEEE **Years:** 1965 - Present Most Recent Issue

Submission – Step 1 – in IEEE *Xplore*



The IEEE Open Journal of Antennas and Propagation covers antennas, including analysis, design, development, measurement, standards, and testing; radiation, propagation, and the interaction of electromagnetic waves with discrete and continuous media; and applications and systems pertinent to antennas, propagation, and sensing, such as applied optics, millimeter-and sub-millimeter-wave techniques, antenna signal processing and control, radio astronomy, and propagation and radiation aspects of terrestrial and space-based communication, including wireless, mobile, satellite, and telecommunications at all frequencies.

The IEEE Open Journal of Antennas and Propagation (IEEE OJAP) welcomes contributions covering aspects from theory and design to applied engineering innovations, topical review, and perspective articles. The journal publishes papers on mature topics as well as on emerging fields, including those at the nexus of other engineering and science disciplines that are dependent upon antennas and propagation. IEEE OJAP is committed to supporting open and transparent research exchange and enabling authors to embrace best practices in data and code sharing.

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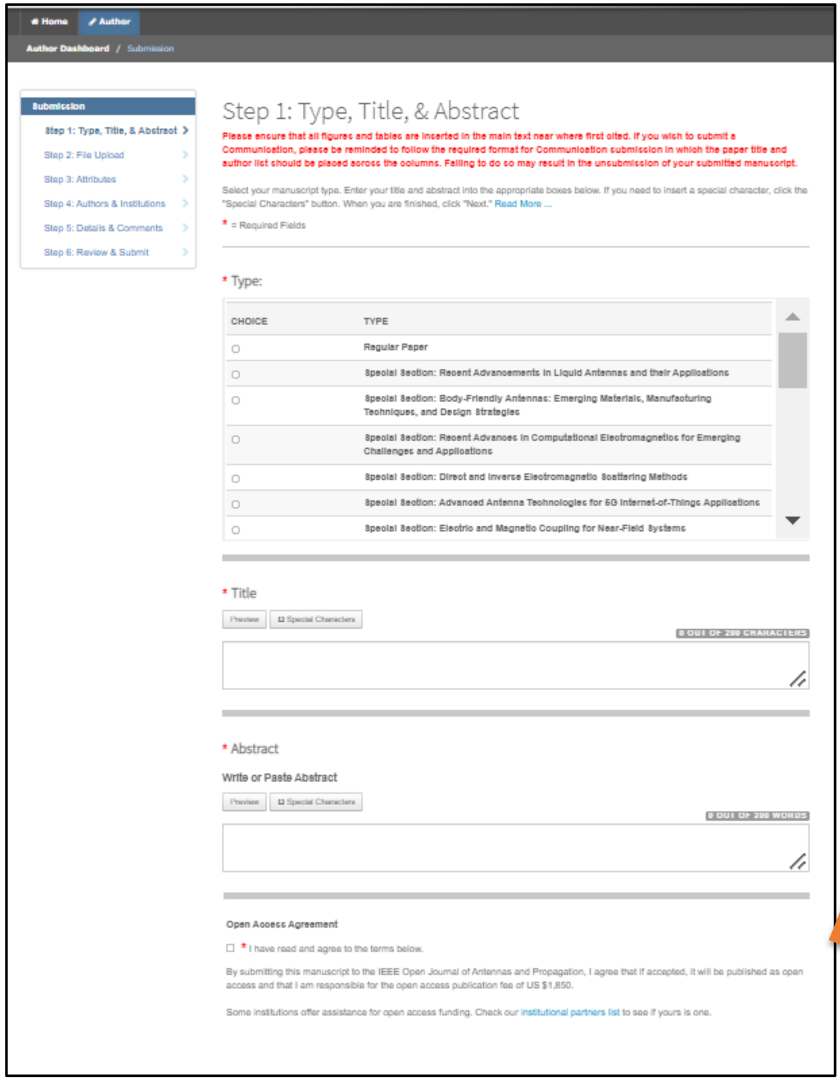
Submission process

- The corresponding author will complete the submission process.
- Authors submitting to fully OA journals will be asked to accept OA terms and charges during Step 1.

Submission – Step 1 – Fully OA journal



Step 1: Type, Title, & Abstract

Please ensure that all figures and tables are inserted in the main text near where first cited. If you wish to submit a Communication, please be reminded to follow the required format for Communication submission in which the paper title and author list should be placed across the columns. Failing to do so may result in the unsubmission of your submitted manuscript.

Select your manuscript type. Enter your title and abstract into the appropriate boxes below. If you need to insert a special character, click the "Special Characters" button. When you are finished, click "Next." Read More ...

* = Required Fields

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CHOICE	TYPE
○	Regular Paper
○	Special Section: Recent Advancements in Liquid Antennas and their Applications
○	Special Section: Body-Friendly Antennas: Emerging Materials, Manufacturing Techniques, and Design Strategies
○	Special Section: Recent Advances in Computational Electromagnetics for Emerging Challenges and Applications
○	Special Section: Direct and Inverse Electromagnetic Scattering Methods
○	Special Section: Advanced Antenna Technologies for 5G Internet-of-Things Applications
○	Special Section: Electric and Magnetic Coupling for Near-Field Systems

* Title

* Abstract

Write or Paste Abstract

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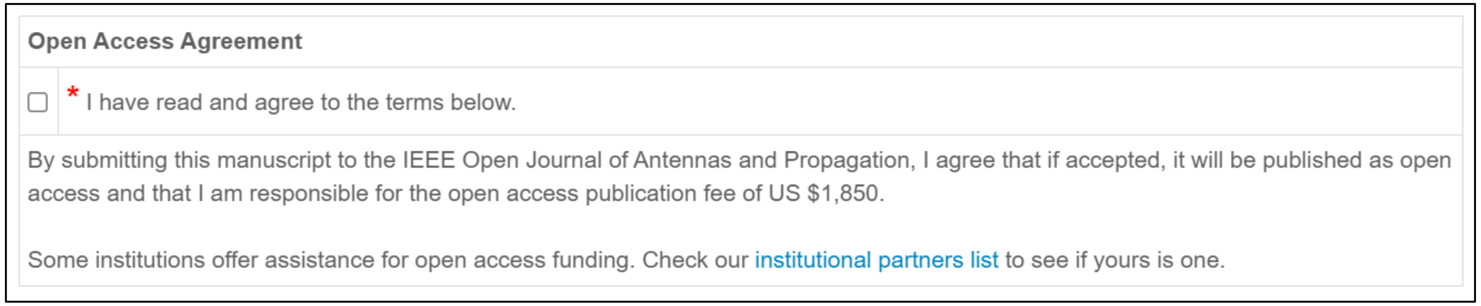
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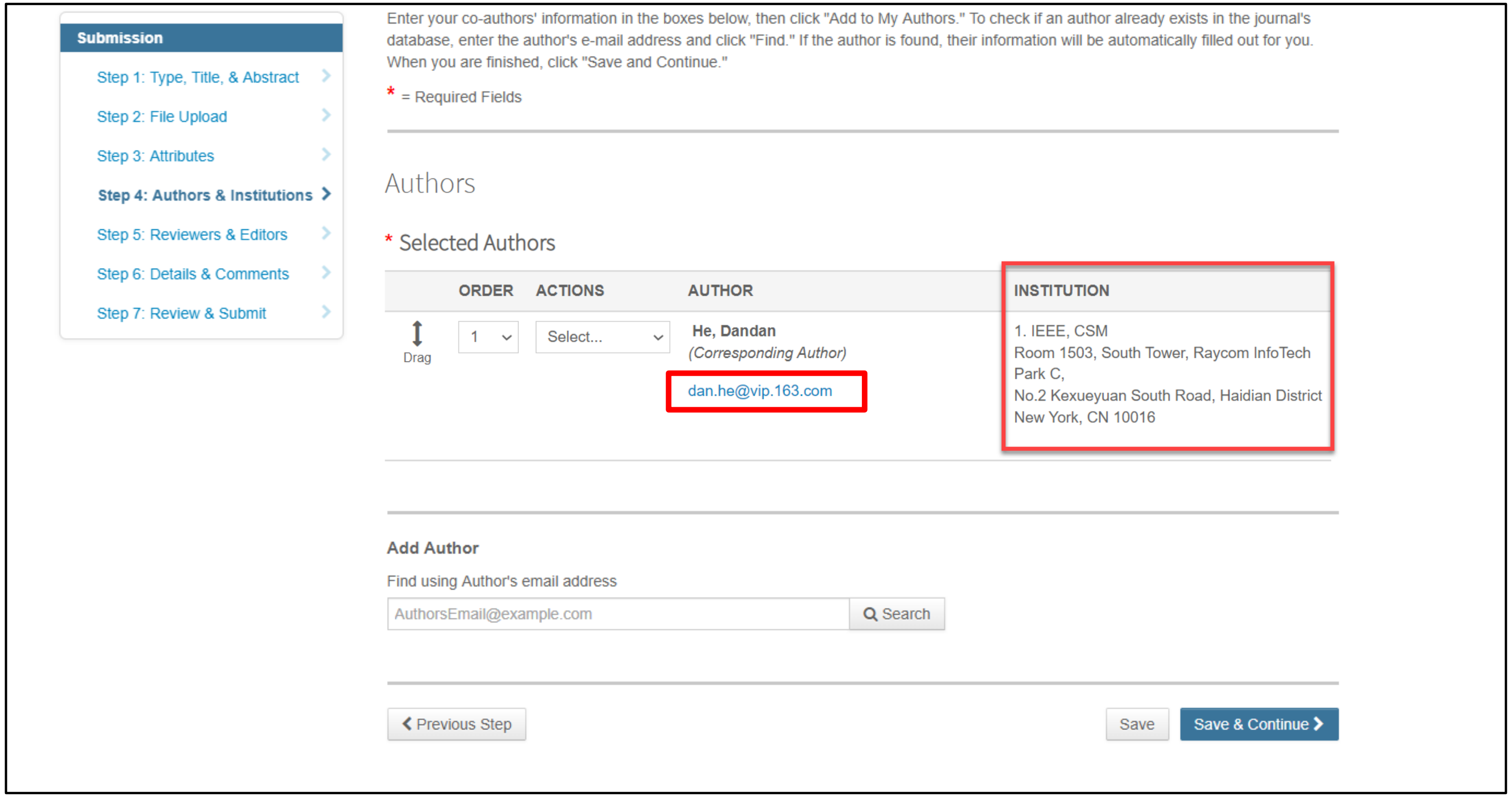

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* Selected Authors

	ORDER	ACTIONS	AUTHOR	INSTITUTION
Drag	1	Select...	**He, Dandan** *(Corresponding Author)* dan.he@vip.163.com	1. IEEE, CSM Room 1503, South Tower, Raycom InfoTech Park C, No.2 Kexueyuan South Road, Haidian District New York, CN 10016

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Find using Author's email address

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Submission – Step 4

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Drag	1	Select...	**He, Dandan** *(Corresponding Author)* dan.he@vip.163.com	1. ⚠ Beijing,

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Authors

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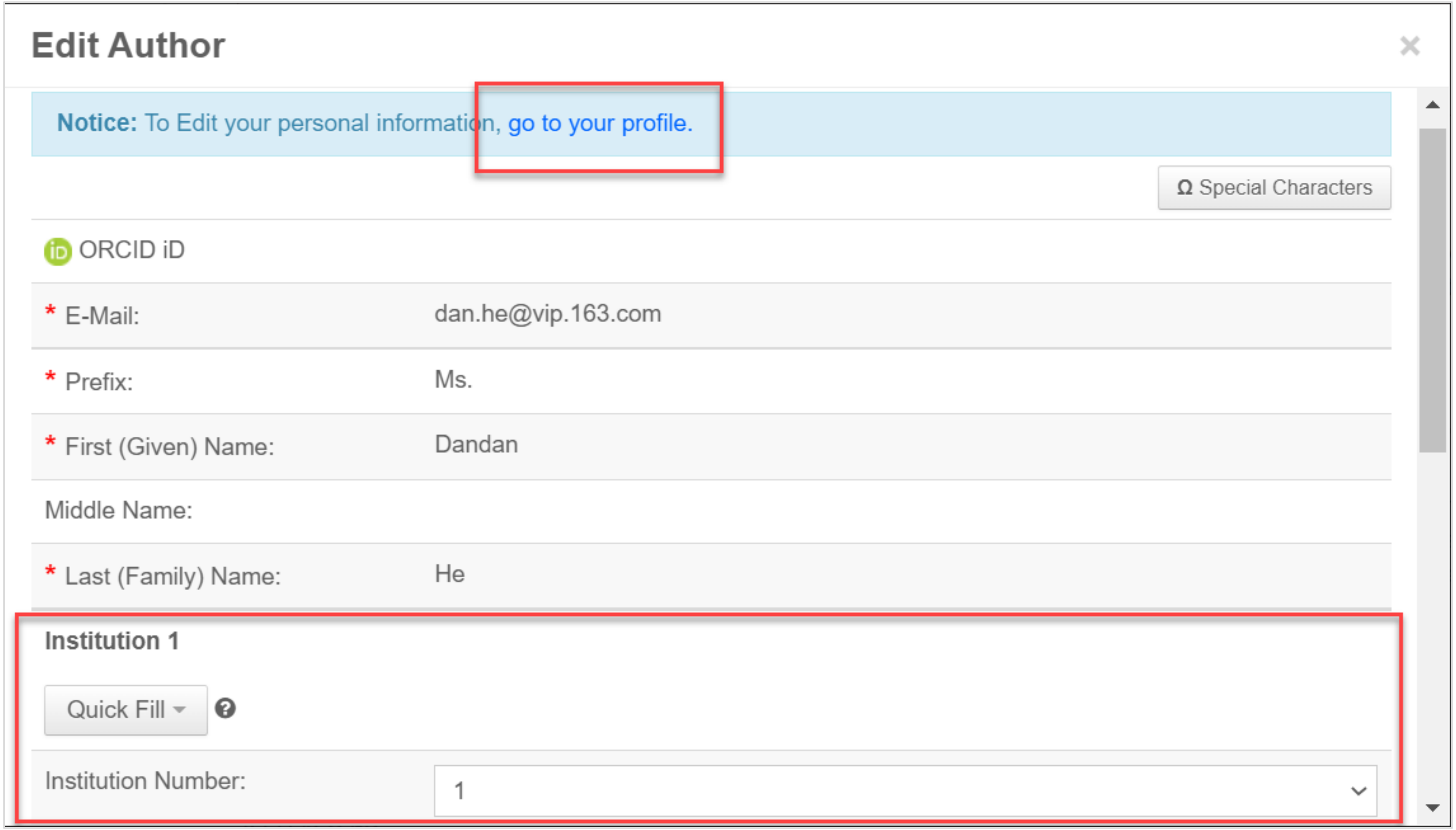

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Middle Name:	
* Last (Family) Name:	He

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Institution Number: 1

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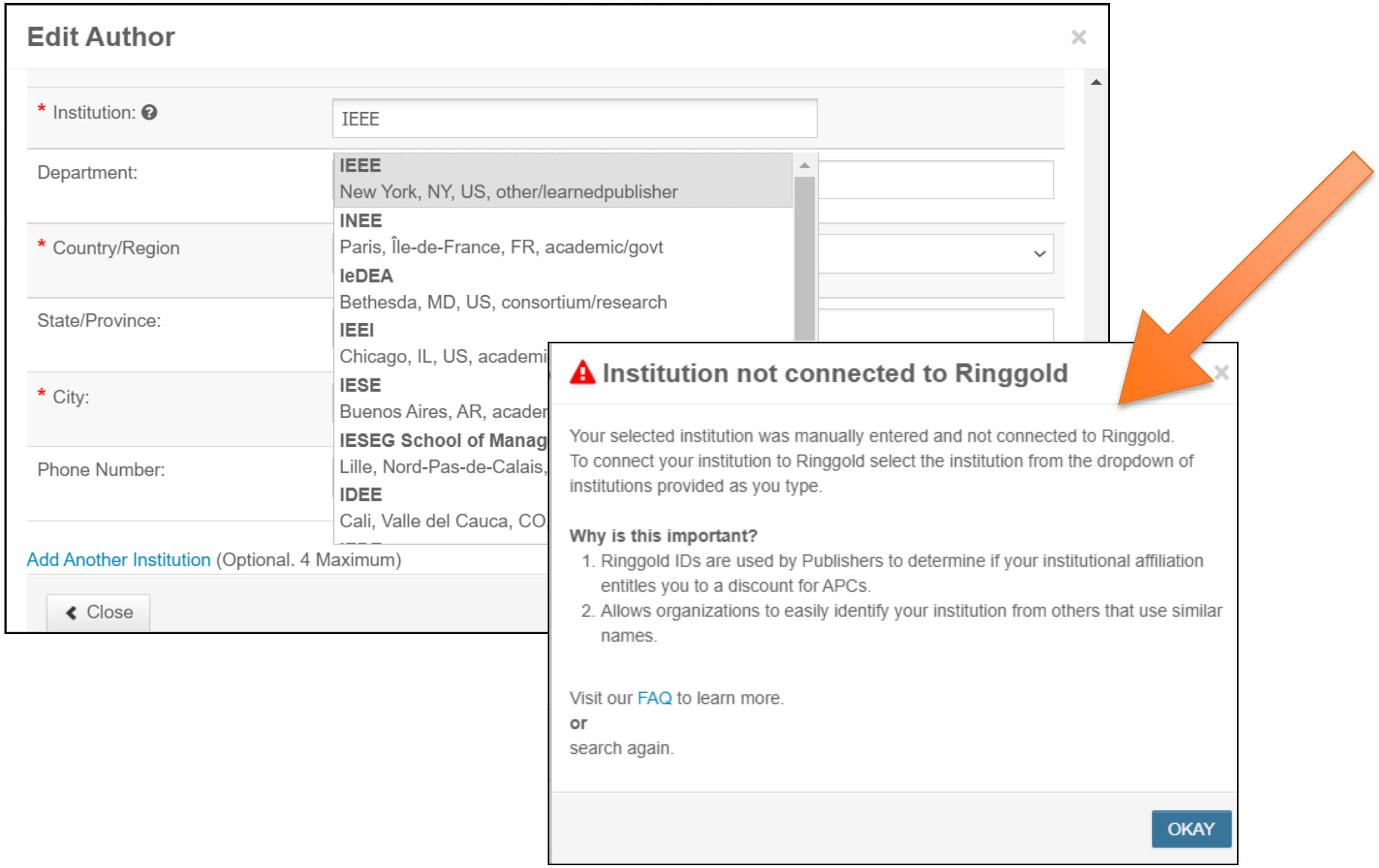

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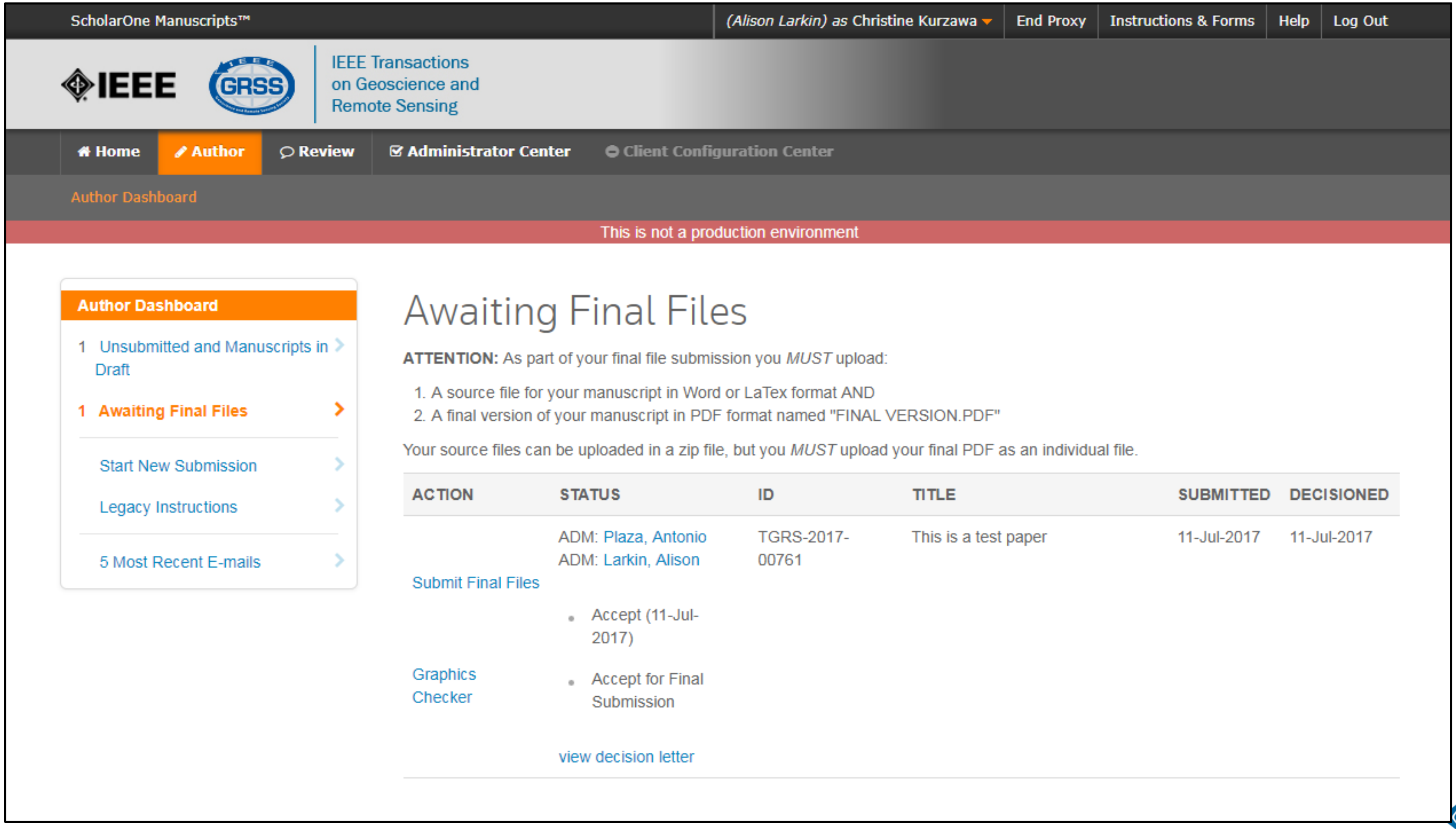
- After acceptance, author can contact ieee_oa@hintoninfo.com for APC Token information in your institution.

Post acceptance – final files upload



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ATTENTION: As part of your final file submission you *MUST* upload:

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ACTION	STATUS	ID	TITLE	SUBMITTED	DECISIONED
Submit Final Files Graphics Checker	ADM: Plaza, Antonio ADM: Larkin, Alison • Accept (11-Jul-2017) • Accept for Final Submission view decision letter	TGRS-2017-00761	This is a test paper	11-Jul-2017	11-Jul-2017

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2. Confirm the paper’s originality
3. OA Authors must agree “to pay” an APC (Article Processing Charge)
4. Select and sign CC-BY license type
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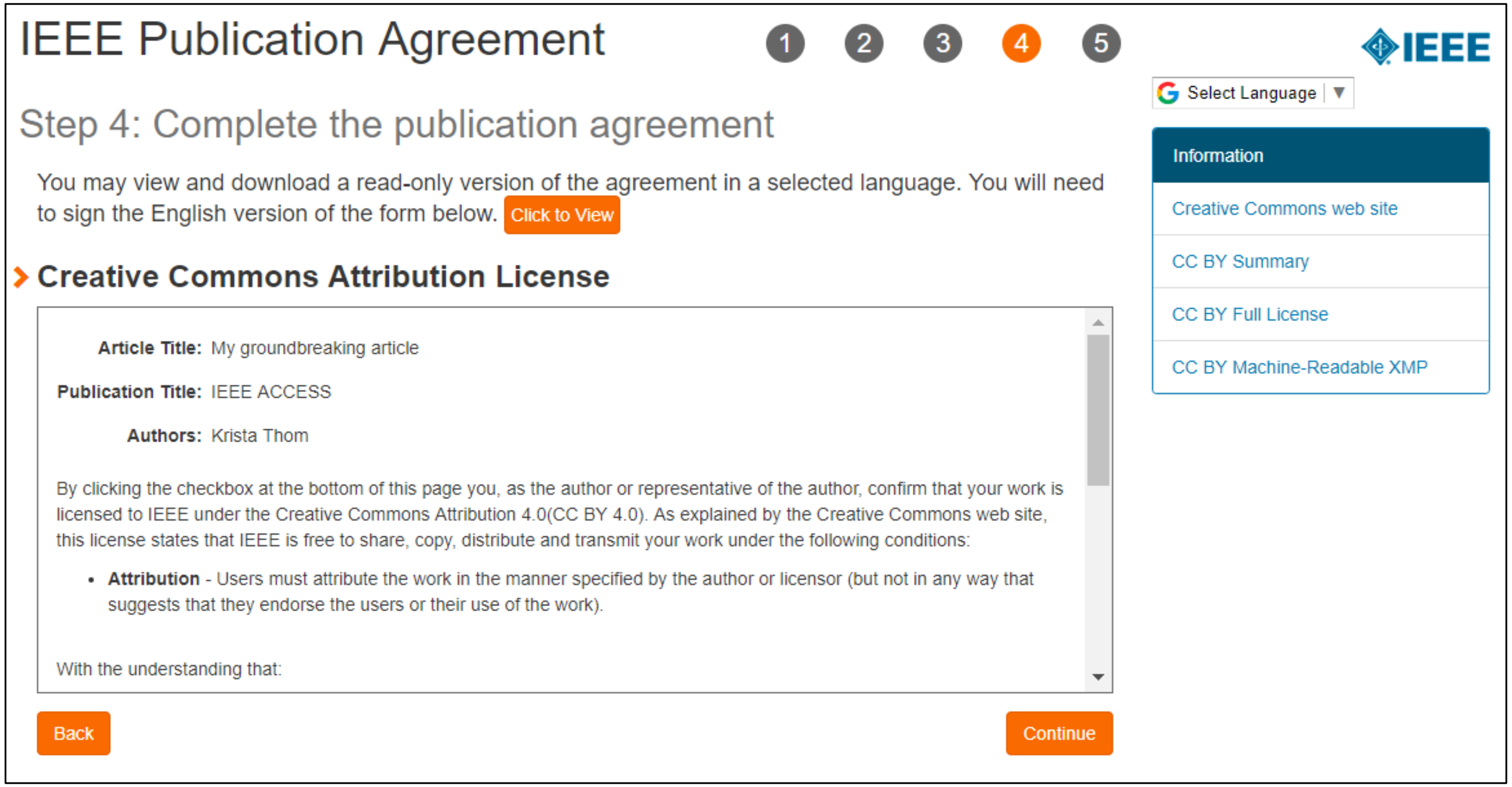

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Step 4: Complete the publication agreement

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Article Title: My groundbreaking article

Publication Title: IEEE ACCESS

Authors: Krista Thom

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- An APC Token application is automatically sent to the institution when a manuscript matches the profile.
- Eligible authors will receive email from Hinton
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- Institutional profiles are matched using author-provided affiliation data including email domains and/or Ringgold IDs. Wild cards can also be used when matching on email domain.

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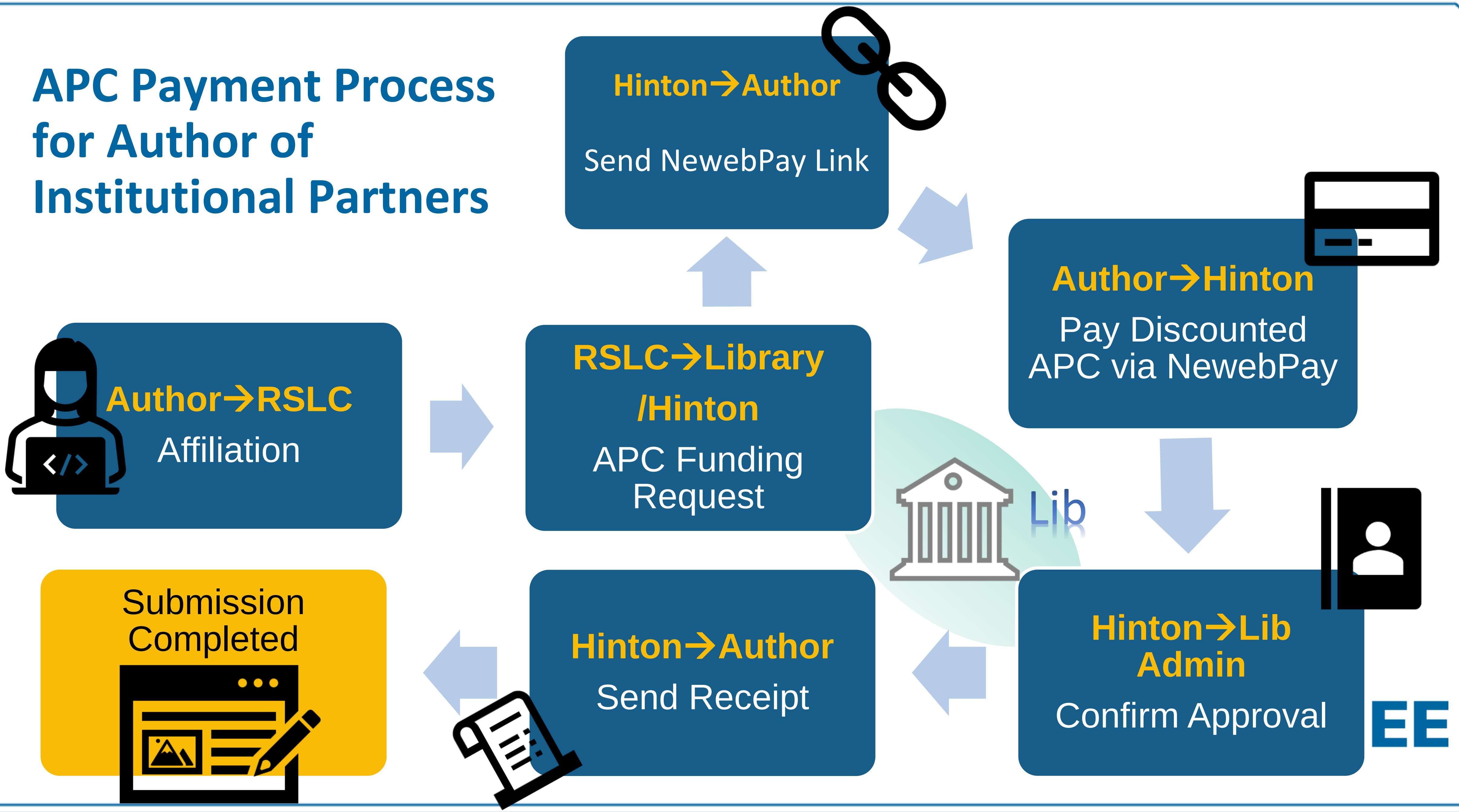

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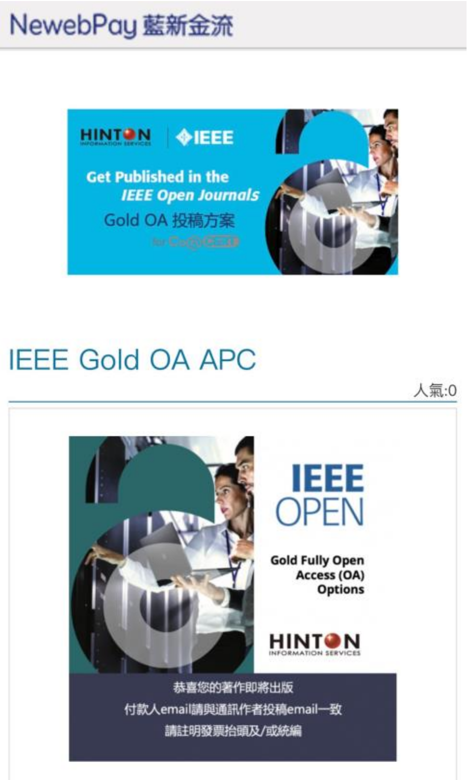

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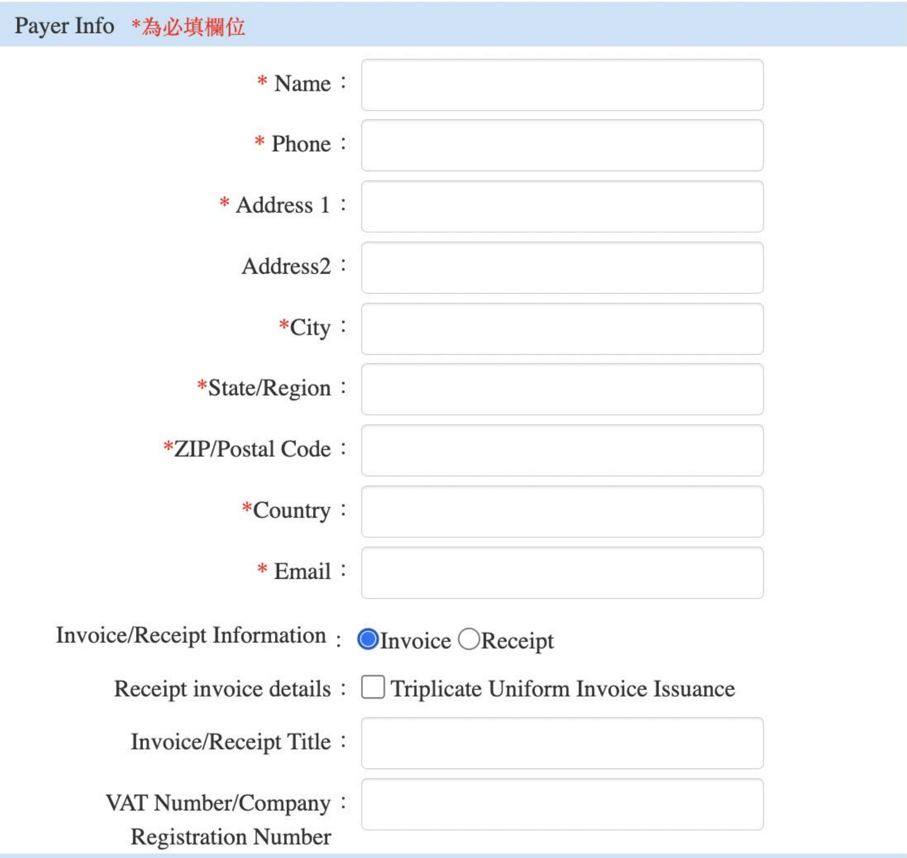

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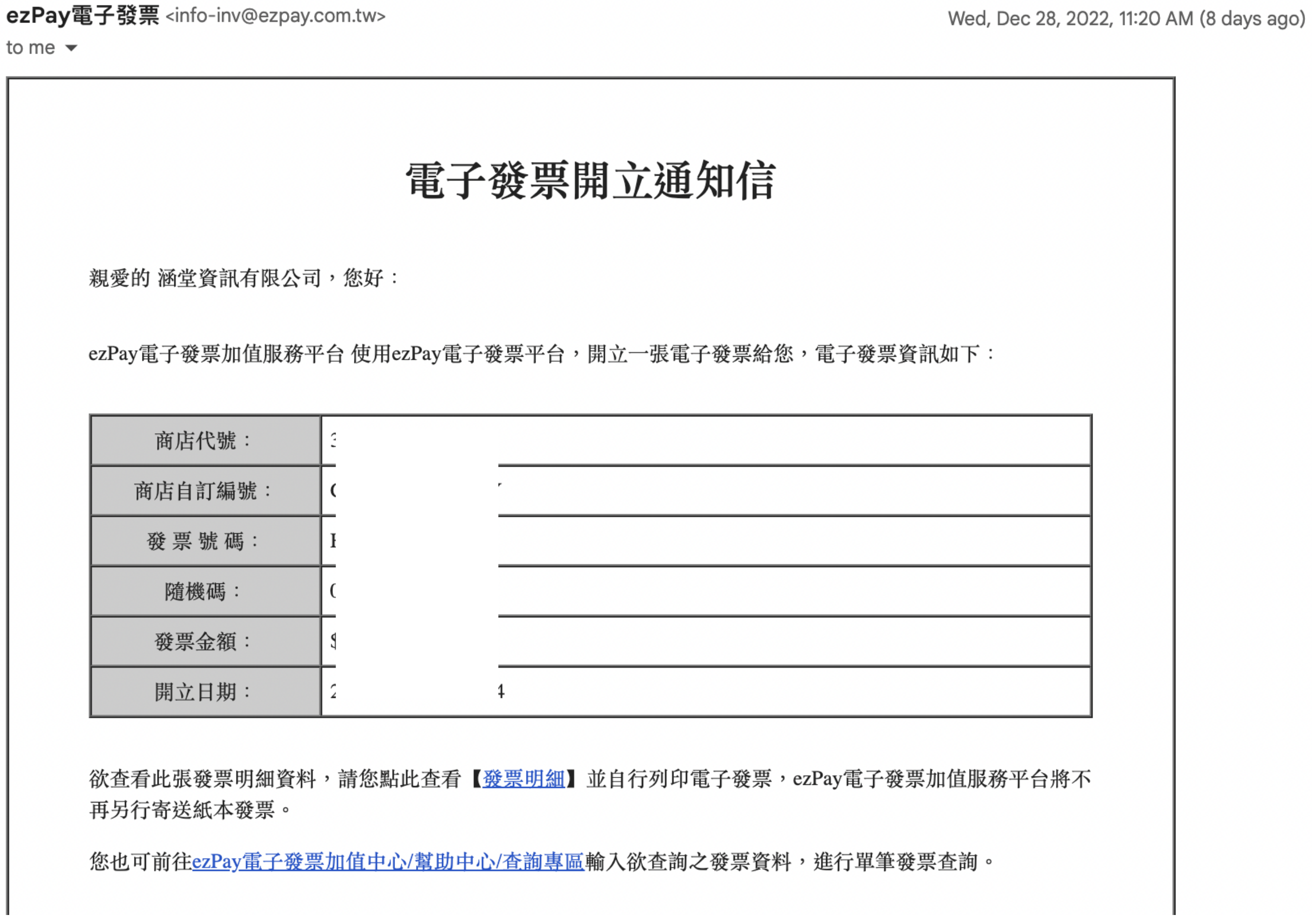

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Wed, Dec 28, 2022, 11:20 AM (8 days ago)

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Administrator Process

Responding to funding requests, reporting, and setting alerts

Account Administrator capabilities

- The Institution Portal in RightsLink for Scientific Communications (RLSC) allows administrators to:
  - View pending transactions.
  - Approve or deny funding requests.
  - Manage notifications.
  - Pull transaction reports.
- Administrators can also set IEEE *Xplore* alerts to monitor published articles.

Notifications

IEEE Access

One of your researchers has had a manuscript accepted for publication.

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A recently accepted manuscript has been matched to your special APC billing profile, TEST OAUltd Liverpool John Moores. The author(s) will be notified of acceptance and given the opportunity through the RightsLink platform to request funding from you for applicable APC charges. If they do, you will have the opportunity to approve or deny the request from your RightsLink Funding Requests page.

Manuscript Details
Accept Date: 08-Jan-2020
Publisher: Institute of Electrical and Electronics Engineers
DOI: 10.1000/IEEE_Test01082019a
Publication: IEEE Access
Article Title: Test Manuscript Test01082019a
Author(s): Scott Allison sallison@copyright.com

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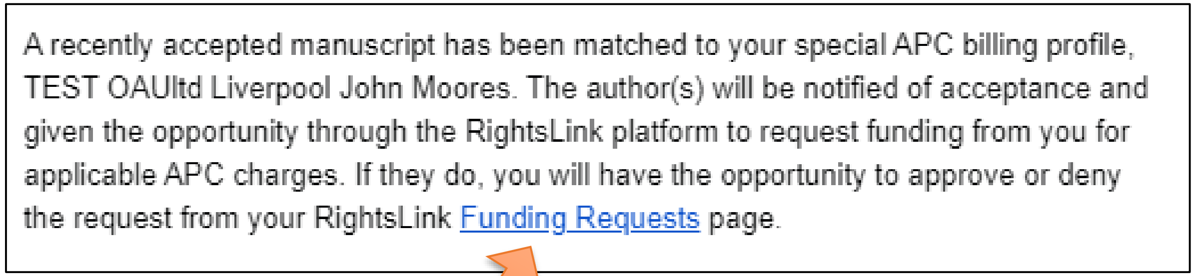
- Eligible articles are identified using author-supplied affiliation data and matched using Ringgold IDs and, in some cases, email domains.



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Clicking on the “Funding Requests” link will bring administrators to their RLSC institutional portal.

Notifications

Your author has requested APC funding.

Dear IEEE UAT,

Your author has requested funding

Request Details
Request Date: 18-Apr-2019
Publisher: Institute of Electrical and Electronics Engineers
Publication: IEEE Access
Article Title: Test Manuscript Matching Partner (15% Disct)
Author(s): Sheryl Holt, Jennifer Goodrich

Please click here to view details and respond.

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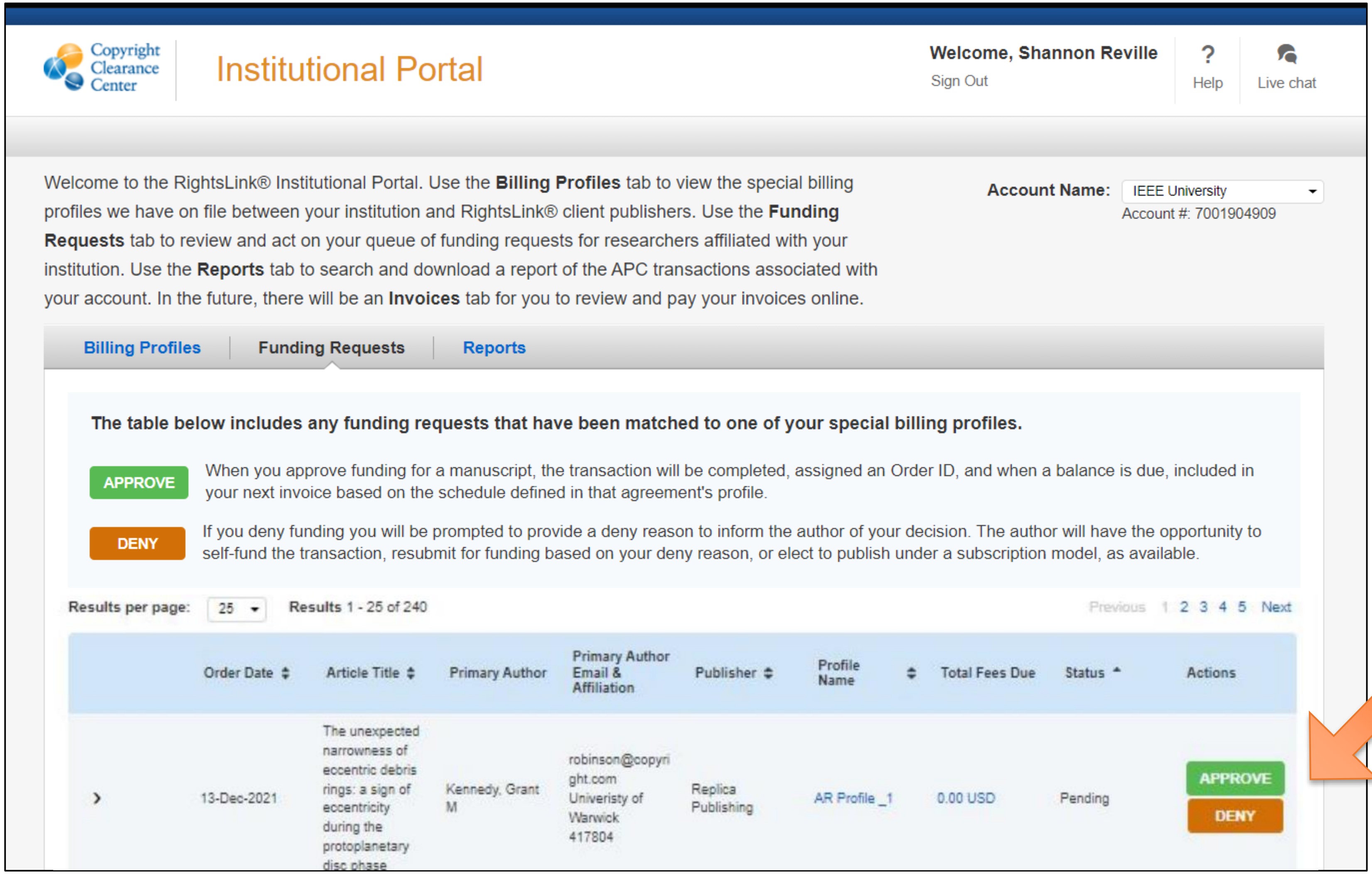
Administrators will receive an email when an eligible author chooses to seek funding under their account.

This email is sent in both touch free and traditional workflows.

Account dashboard



Institutional Portal

Welcome, Shannon Reville
Sign Out

Welcome to the RightsLink® Institutional Portal. Use the **Billing Profiles** tab to view the special billing profiles we have on file between your institution and RightsLink® client publishers. Use the **Funding Requests** tab to review and act on your queue of funding requests for researchers affiliated with your institution. Use the **Reports** tab to search and download a report of the APC transactions associated with your account. In the future, there will be an **Invoices** tab for you to review and pay your invoices online.

Account Name: IEEE University
Account #: 7001904909

The table below includes any funding requests that have been matched to one of your special billing profiles.

APPROVE When you approve funding for a manuscript, the transaction will be completed, assigned an Order ID, and when a balance is due, included in your next invoice based on the schedule defined in that agreement's profile.

DENY If you deny funding you will be prompted to provide a deny reason to inform the author of your decision. The author will have the opportunity to self-fund the transaction, resubmit for funding based on your deny reason, or elect to publish under a subscription model, as available.

Results per page: 25 **Results** 1 - 25 of 240

	Order Date	Article Title	Primary Author	Primary Author Email & Affiliation	Publisher	Profile Name	Total Fees Due	Status	Actions
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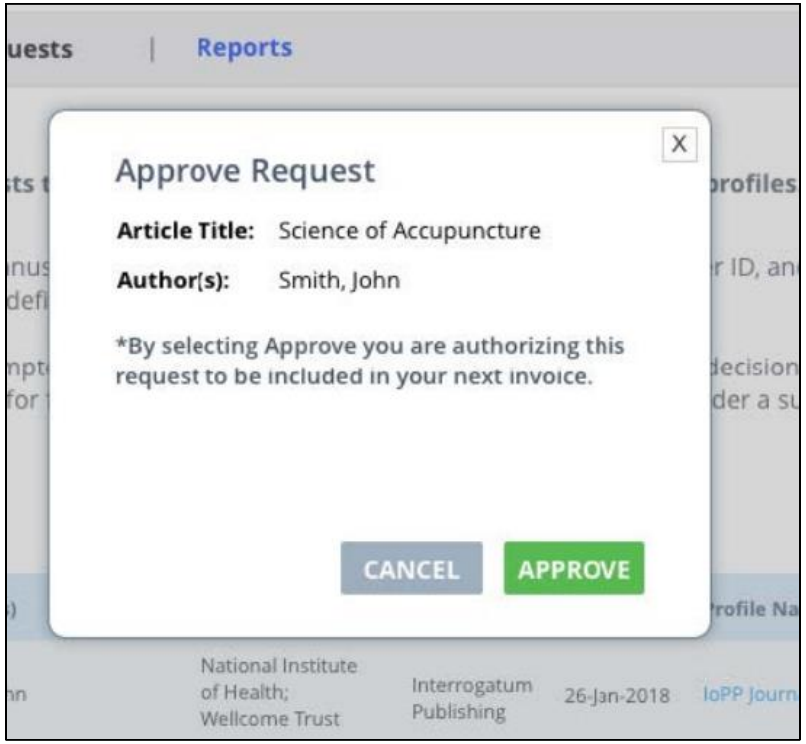
When administrators log in, they will be able to view and respond to outstanding requests.

Approving requests



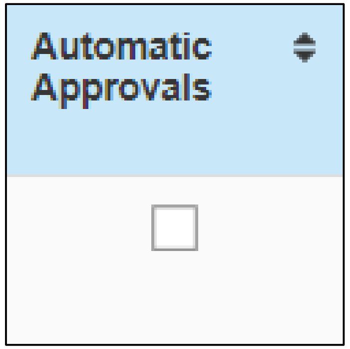
Approve Request

Article Title: Science of Acupuncture

Author(s): Smith, John

*By selecting Approve you are authorizing this request to be included in your next invoice.

Administrators can also choose to approve requests automatically under the “Billing Profiles” tab.



Clicking “Approve” will launch a pop-up box that prompts the administrator to confirm approval. As further confirmation, the author also receives a Funding Approved email.

Additional Resources

IEEE Open
https://open.ieee.org/

CCC RLSC: Resources for Authors
https://www.copyright.com/rlauthorrc/

IEEE Author Center
https://ieeeauthorcenter.ieee.org/

IEEE Author Posting Guidelines
https://www.ieee.org/publications/rights/author-posting-policy.html

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